

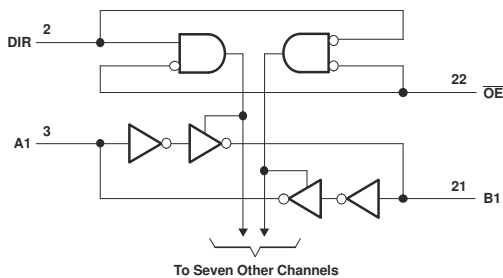
SN74LVC8T245-Q1 具有可配置电压转换和三态输出的 汽车类 8 位双电源总线收发器

1 特性

- 控制输入 V_{IH}/V_{IL} 电平以 V_{CCA} 电压为基准
- V_{CC} 隔离特性 - 如果任何一个 V_{CC} 输入接地 (GND)，所有输出均处于高阻抗状态
- 完全可配置的双轨设计，支持各个端口在 1.65V 至 5.5V 的整个电源电压范围内运行
- 闩锁性能超过 100mA，符合 JESD 78 II 类规范的要求
- ESD 保护性能超过 JESD 22 规范要求
 - 4000V 人体放电模式 (A114-A)
 - 100V 机器放电模型 (A115-A)
 - 1000V 带电器件模型 (C101)

2 应用

- [个人电子产品](#)
- [工业](#)
- [企业](#)
- [电信](#)



逻辑图 (正逻辑)

3 说明

SN74LVC8T245-Q1 是一款具有可配置双电源轨的 8 位同相总线收发器，可支持双向电压电平转换。SN74LVC8T245-Q1 经过优化，可在 V_{CCA} 和 V_{CCB} 设置为 1.65V 至 5.5V 的范围内正常运行。A 端口旨在跟踪 V_{CCA} 。 V_{CCA} 可接受从 1.65V 到 5.5V 范围内的任意电源电压。B 端口旨在跟踪 V_{CCB} 。 V_{CCB} 可接受从 1.65V 至 5.5V 间的任一电源电压值。这可实现 1.8V、2.5V、3.3V 和 5.5V 电压节点间的通用低压双向转换。

SN74LVC8T245-Q1 旨在实现两条数据总线间的异步通信。方向控制 (DIR) 输入和输出使能 (\overline{OE}) 输入的逻辑电平激活 B 端口输出或者 A 端口输出，或者将两个输出端口都置于高阻抗模式。当 B 端口输出被激活时，此器件将数据从 A 总线发送到 B 总线，而当 A 端口输出被激活时，此器件将数据从 B 总线发送到 A 总线。A 端口和 B 端口上的输入电路一直处于激活状态并且必须施加一个逻辑高或低电平，从而防止过大的 I_{CC} 和 I_{CCZ} 。

该器件完全符合使用 I_{off} 的部分断电应用的规范要求。 I_{off} 电路禁用输出，从而可防止其断电时破坏性电流从该器件回流。 V_{CC} 隔离特性可确保只要有任意一个 V_{CC} 输入接地 (GND)，则所有输出均处于高阻抗状态。为了确保加电或断电期间的高阻抗状态， \overline{OE} 应通过一个上拉电阻器被连接至 V_{CC} ；该电阻器的最小值由驱动器的电流吸收能力来决定。

SN74LVC8T245-Q1 器件旨在使控制引脚 (DIR 和 \overline{OE}) 由 V_{CCA} 供电。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 (标称值)
SN74LVC8T245-Q1	PW (TSSOP, 24)	7.80mm × 4.40mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



Table of Contents

1 特性	1	8.1 Overview.....	12
2 应用	1	8.2 Functional Block Diagram.....	12
3 说明	1	8.3 Feature Description.....	12
4 Revision History	2	8.4 Device Functional Modes.....	13
5 Pin Configuration and Functions	3	9 Application and Implementation	14
6 Specifications	4	9.1 Application Information.....	14
6.1 Absolute Maximum Ratings.....	4	9.2 Typical Application.....	14
6.2 ESD Ratings.....	4	10 Power Supply Recommendations	15
6.3 Recommended Operating Conditions.....	5	11 Layout	16
6.4 Thermal Information.....	6	11.1 Layout Guidelines.....	16
6.5 Electrical Characteristics.....	7	11.2 Layout Example.....	16
6.6 Switching Characteristics, $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$	8	12 Device and Documentation Support	17
6.7 Switching Characteristics, $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$	8	12.1 接收文档更新通知.....	17
6.8 Switching Characteristics, $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$	9	12.2 支持资源.....	17
6.9 Switching Characteristics, $V_{CCA} = 5\text{ V} \pm 0.5\text{ V}$	9	12.3 Trademarks.....	17
6.10 Operating Characteristics.....	9	12.4 静电放电警告.....	17
6.11 Typical Characteristics.....	10	12.5 术语表.....	17
7 Parameter Measurement Information	11	13 Mechanical, Packaging, and Orderable Information	17
8 Detailed Description	12		

4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision * (September 2010) to Revision A (December 2022)	Page
• 更新了整个文档中的表格、图和交叉参考的编号格式.....	1
• 添加了 <i>详细说明</i> 部分、 <i>应用和实施</i> 部分、 <i>电源相关建议</i> 部分和 <i>布局布线</i> 部分.....	1
• Added thermal values.....	6

5 Pin Configuration and Functions

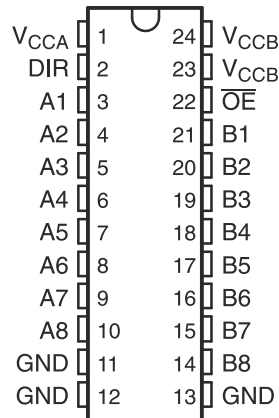


图 5-1. PW Package, 24-Pin TSSOP (Top View)

表 5-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
A1	3	I/O	Input/output A1. Referenced to V_{CCA} .
A2	4	I/O	Input/output A2. Referenced to V_{CCA} .
A3	5	I/O	Input/output A3. Referenced to V_{CCA} .
A4	6	I/O	Input/output A4. Referenced to V_{CCA} .
A5	7	I/O	Input/output A5. Referenced to V_{CCA} .
A6	8	I/O	Input/output A6. Referenced to V_{CCA} .
A7	9	I/O	Input/output A7. Referenced to V_{CCA} .
A8	10	I/O	Input/output A8. Referenced to V_{CCA} .
B1	21	I/O	Input/output B1. Referenced to V_{CCB} .
B2	20	I/O	Input/output B2. Referenced to V_{CCB} .
B3	19	I/O	Input/output B3. Referenced to V_{CCB} .
B4	18	I/O	Input/output B4. Referenced to V_{CCB} .
B5	17	I/O	Input/output B5. Referenced to V_{CCB} .
B6	16	I/O	Input/output B6. Referenced to V_{CCB} .
B7	15	I/O	Input/output B7. Referenced to V_{CCB} .
B8	14	I/O	Input/output B8. Referenced to V_{CCB} .
DIR	2	I	Direction-control signal.
GND	11, 12, 13	G	Ground
\overline{OE}	22	I	3-state output-mode enables. Pull \overline{OE} high to place all outputs in 3-state mode. Referenced to V_{CCA} .
V_{CCA}	1	P	A-port supply voltage. $1.65\text{ V} \leq V_{CCA} \leq 5.5\text{ V}$
V_{CCB}	23, 24	P	B-port supply voltage. $1.65\text{ V} \leq V_{CCB} \leq 5.5\text{ V}$

(1) I = input, O = output, P = power

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

(1)		MIN	MAX	UNIT	
Supply voltage range, V_{CCA} , V_{CCB}		- 0.5	6.5	V	
V_I	Input voltage range ⁽²⁾	I/O ports (A port)	- 0.5	6.5	V
		I/O ports (B port)	- 0.5	6.5	
		Control inputs	- 0.5	6.5	
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	A port	- 0.5	6.5	V
		B port	- 0.5	6.5	
V_O	Voltage range applied to any output in the high or low state ^{(2) (3)}	A port	- 0.5	$V_{CCA} + 0.5$	V
		B port	- 0.5	$V_{CCB} + 0.5$	
I_{IK}	Input clamp current	$V_I < 0$	- 50	mA	
I_{OK}	Output clamp current	$V_O < 0$	- 50	mA	
I_O	Continuous output current		± 50	mA	
	Continuous current through each V_{CCA} , V_{CCB} , and GND		± 100	mA	
T_{stg}	Storage temperature	-65	150	°C	
T_J	Junction temperature		150	°C	

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The output positive-voltage rating may be exceeded up to 6.5 V maximum if the output current rating is observed.

6.2 ESD Ratings

			MIN	MAX	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	- 4000	4000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	- 1000	1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

(1) (2) (3) (4) (5) (6)

			V _{CCI}	V _{CCO}	MIN	MAX	UNIT
V _{CCA}	Supply voltage				1.65	5.5	V
V _{CCB}					1.65	5.5	
V _{IH}	High-level input voltage	Data inputs ⁽⁵⁾	1.65 V to 1.95 V		V _{CCI} × 0.65		V
			2.3 V to 2.7 V		1.7		
			3 V to 3.6 V		2		
			4.5 V to 5.5 V		V _{CCI} × 0.7		
V _{IL}	Low-level input voltage	Data inputs ⁽⁵⁾	1.65 V to 1.95 V		V _{CCI} × 0.35		V
			2.3 V to 2.7 V		0.7		
			3 V to 3.6 V		0.8		
			4.5 V to 5.5 V		V _{CCI} × 0.3		
V _{IH}	High-level input voltage	Control inputs (referenced to V _{CCA}) ⁽⁶⁾	1.65 V to 1.95 V		V _{CCA} × 0.65		V
			2.3 V to 2.7 V		1.7		
			3 V to 3.6 V		2		
			4.5 V to 5.5 V		V _{CCA} × 0.7		
V _{IL}	Low-level input voltage	Control inputs (referenced to V _{CCA}) ⁽⁶⁾	1.65 V to 1.95 V		V _{CCA} × 0.35		V
			2.3 V to 2.7 V		0.7		
			3 V to 3.6 V		0.8		
			4.5 V to 5.5 V		V _{CCA} × 0.3		
V _I	Input voltage	Control inputs			0	5.5	V
V _{I/O}	Input/output voltage	Active state			0	V _{CCO}	V
		3-State			0	5.5	V
I _{OH}	High-level output current		1.65 V to 1.95 V			-4	mA
			2.3 V to 2.7 V			-8	
			3 V to 3.6 V			-24	
			4.5 V to 5.5 V			-32	
I _{OL}	Low-level output current		1.65 V to 1.95 V			4	mA
			2.3 V to 2.7 V			8	
			3 V to 3.6 V			24	
			4.5 V to 5.5 V			32	
Δt/ Δv ⁽⁷⁾	Input transition rise or fall rate	Data inputs	1.65 V to 1.95 V			20	ns/V
			2.3 V to 2.7 V			20	
			3 V to 3.6 V			10	
			4.5 V to 5.5 V			5	
T _A	Operating free-air temperature				-40	125	°C

- (1) V_{CCI} is the V_{CC} associated with the data input port.
- (2) V_{CCO} is the V_{CC} associated with the output port.
- (3) All unused or driven (floating) data inputs (I/Os) of the device must be held at logic HIGH or LOW (preferably V_{CCI} or GND) to ensure proper device operation and minimize power. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
- (4) All unused control inputs must be held at V_{CCA} or GND to ensure proper device operation and minimize power consumption.
- (5) For V_{CCI} values not specified in the data sheet, V_{IH} min = V_{CCI} × 0.7 V, V_{IL} max = V_{CCI} × 0.3 V.
- (6) For V_{CCA} values not specified in the data sheet, V_{IH} min = V_{CCA} × 0.7 V, V_{IL} max = V_{CCA} × 0.3 V.
- (7) Maximum input transition rate with < 4 channels switching simultaneously.

6.4 Thermal Information

THERMAL METRIC ¹		PW	UNIT
		24 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	100.6	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	44.7	
$R_{\theta JB}$	Junction-to-board thermal resistance	55.8	°C/W
ψ_{JT}	Junction-to-top characterization parameter	6.8	°C/W
ψ_{JB}	Junction-to-board characterization parameter	55.4	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

6.5 Electrical Characteristics

 over recommended operating free-air temperature range (unless otherwise noted) ⁽¹⁾ ⁽²⁾ ⁽³⁾

PARAMETER	TEST CONDITIONS	V _{CCA}	V _{CCB}	T _A = 25°C			T _A = -40°C to 125°C			UNIT	
				MIN	TYP	MAX	MIN	TYP	MAX		
V _{OH}	I _{OH} = - 100 μA, V _I = V _{IH}	1.65 V to 4.5 V	1.65 V to 4.5 V				V _{CCO} - 0.1		V		
	I _{OH} = - 4 mA, V _I = V _{IH}	1.65 V	1.65 V				1.2				
	I _{OH} = - 8 mA, V _I = V _{IH}	2.3 V	2.3 V				1.9				
	I _{OH} = - 24 mA, V _I = V _{IH}	3 V	3 V				2.4				
	I _{OH} = - 32 mA, V _I = V _{IH}	4.5 V	4.5 V				3.8				
V _{OL}	I _{OL} = 100 μA, V _I = V _{IL}	1.65 V to 4.5 V	1.65 V to 4.5 V					0.1	V		
	I _{OL} = 4 mA, V _I = V _{IL}	1.65 V	1.65 V					0.45			
	I _{OL} = 8 mA, V _I = V _{IL}	2.3 V	2.3 V					0.3			
	I _{OL} = 24 mA, V _I = V _{IL}	3 V	3 V					0.55			
	I _{OL} = 32 mA, V _I = V _{IL}	4.5 V	4.5 V					0.55			
I _I	DIR	V _I = V _{CCA} or GND	1.65 V to 5.5 V	1.65 V to 5.5 V				±1	±2	μA	
I _{off}	A or B port	V _I or V _O = 0 to 5.5 V	0 V	0 to 5.5 V				±2	±11	μA	
			0 to 5.5 V	0 V				±2	±11		
I _{OZ}	A or B port	V _O = V _{CCO} or GND, OE = V _{IH}	1.65 V to 5.5 V	1.65 V to 5.5 V				±1	±6	μA	
I _{CCA}	V _I = V _{CCI} or GND, I _O = 0	1.65 V to 5.5 V	1.65 V to 5.5 V						20	μA	
		5 V	0 V						20		
		0 V	5 V						- 10		
I _{CCB}	V _I = V _{CCI} or GND, I _O = 0	1.65 V to 5.5 V	1.65 V to 5.5 V						20	μA	
		5 V	0 V						- 10		
		0 V	5 V						20		
I _{CCA} + I _{CCB}	V _I = V _{CCI} or GND, I _O = 0	1.65 V to 5.5 V	1.65 V to 5.5 V						40	μA	
Δ I _{CCA}	A port	One A port at V _{CCA} - 0.6 V, DIR at V _{CCA} , B port = open	3 V to 5.5 V	3 V to 5.5 V						50	μA
	DIR	DIR at V _{CCA} - 0.6 V, B port = open, A port at V _{CCA} or GND									
Δ I _{CCB}	B port	One B port at V _{CCB} - 0.6 V, DIR at GND, A port = open	3 V to 5.5 V	3 V to 5.5 V						50	μA
C _i	Control inputs	V _I = V _{CCA} or GND	3.3 V	3.3 V				4		5	pF
C _{io}	A or B port	V _O = V _{CCA/B} or GND	3.3 V	3.3 V				8.5		10	pF

(1) V_{CCO} is the V_{CC} associated with the output port.

(2) V_{CCI} is the V_{CC} associated with the input port.

(3) All unused control inputs must be held at V_{CCA} or GND to ensure proper device operation and minimize power consumption.

6.6 Switching Characteristics, $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$ (unless otherwise noted) (see [Figure 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	B	1.7	25.9	1.3	13.2	1	11.4	0.8	11.1	ns
t_{PHL}											
t_{PLH}	B	A	0.9	28.8	0.8	27.6	0.7	27.4	0.7	27.4	ns
t_{PHL}											
t_{PHZ}	\overline{OE}	A	1.5	33.6	1.5	33.4	1.5	33.3	1.4	33.2	ns
t_{PLZ}											
t_{PHZ}	\overline{OE}	B	2.4	36.2	1.9	17.1	1.7	16	1.3	14.3	ns
t_{PLZ}											
t_{PZH}	\overline{OE}	A	0.4	28	0.4	27.8	0.4	27.7	0.4	27.7	ns
t_{PZL}											
t_{PZH}	\overline{OE}	B	1.8	40	1.5	20	1.2	16.6	0.9	14.8	ns
t_{PZL}											

6.7 Switching Characteristics, $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$ (unless otherwise noted) (see [Figure 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	B	1.5	25.4	1.2	13	0.8	10.2	0.6	8.8	ns
t_{PHL}											
t_{PLH}	B	A	1.2	13.3	1	13.1	1	12.9	0.9	12.8	ns
t_{PHL}											
t_{PHZ}	\overline{OE}	A	1.4	13	1.4	13	1.4	13	1.4	13	ns
t_{PLZ}											
t_{PHZ}	\overline{OE}	B	2.3	33.6	1.8	15	1.7	14.3	0.9	10.9	ns
t_{PLZ}											
t_{PZH}	\overline{OE}	A	1	17.2	1	17.3	1	17.2	1	17.3	ns
t_{PZL}											
t_{PZH}	\overline{OE}	B	1.7	32.2	1.5	18.1	1.2	14.1	1	11.2	ns
t_{PZL}											

6.8 Switching Characteristics, $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see [Figure 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	B	1.5	25.2	1.1	12.8	0.8	10.3	0.5	10.4	ns
t_{PHL}											
t_{PLH}	B	A	0.8	11.2	0.8	10.2	0.7	10.1	0.6	10	ns
t_{PHL}											
t_{PHZ}	\overline{OE}	A	1.6	12.2	1.6	12.2	1.6	12.2	1.6	12.2	ns
t_{PLZ}											
t_{PHZ}	\overline{OE}	B	2.1	33	1.7	14.3	1.5	12.6	0.8	10.3	ns
t_{PLZ}											
t_{PZH}	\overline{OE}	A	0.8	14.1	0.8	13.6	0.8	13.2	0.8	13.6	ns
t_{PZL}											
t_{PZH}	\overline{OE}	B	1.8	31.7	1.4	18.4	1.1	12.9	0.9	10.9	ns
t_{PZL}											

6.9 Switching Characteristics, $V_{CCA} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Figure 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	B	1.5	25.4	1	12.8	0.7	10	0.4	8.2	ns
t_{PHL}											
t_{PLH}	B	A	0.7	11	0.4	8.8	0.3	8.5	0.3	8.3	ns
t_{PHL}											
t_{PHZ}	\overline{OE}	A	0.3	9.4	0.3	9.4	0.3	9.4	0.3	9.4	ns
t_{PLZ}											
t_{PHZ}	\overline{OE}	B	2	32.7	1.6	13.7	1.4	12	0.7	9.7	ns
t_{PLZ}											
t_{PZH}	\overline{OE}	A	0.7	10.9	0.7	10.9	0.7	10.9	0.7	10.9	ns
t_{PZL}											
t_{PZH}	\overline{OE}	B	1.5	31.6	1.3	18.4	1	13.7	0.9	10.7	ns
t_{PZL}											

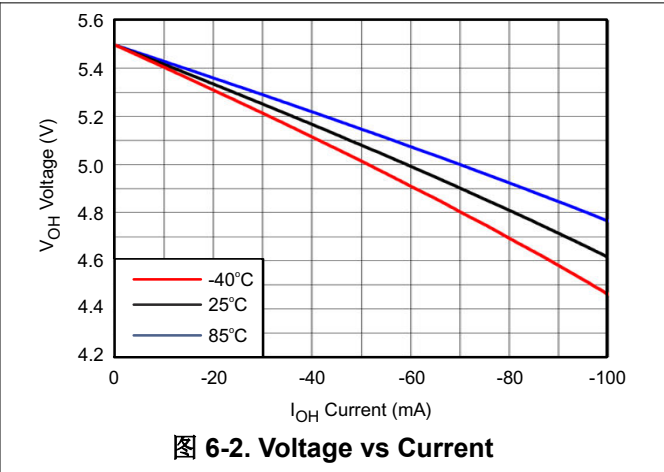
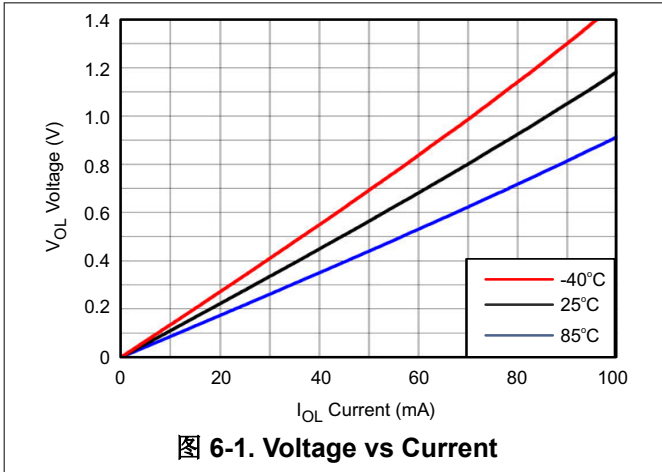
6.10 Operating Characteristics

$T_A = 25^\circ\text{C}$

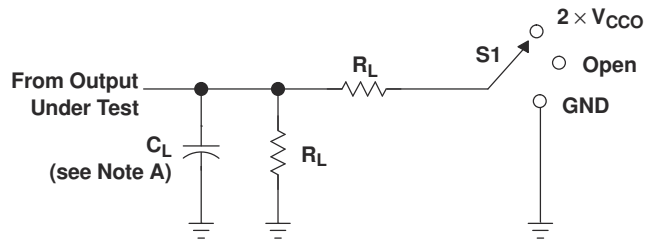
PARAMETER	TEST CONDITIONS	$V_{CCA} = V_{CCB} = 1.8\text{ V}$	$V_{CCA} = V_{CCB} = 2.5\text{ V}$	$V_{CCA} = V_{CCB} = 3.3\text{ V}$	$V_{CCA} = V_{CCB} = 5\text{ V}$	UNIT
		TYP	TYP	TYP	TYP	
C_{pdA} ⁽¹⁾	A-port input, B-port output	2	2	2	3	pF
	B-port input, A-port output	12	13	13	16	
C_{pdB} ⁽¹⁾	A-port input, B-port output	13	13	14	16	
	B-port input, A-port output	2	2	2	3	

(1) Power dissipation capacitance per transceiver

6.11 Typical Characteristics



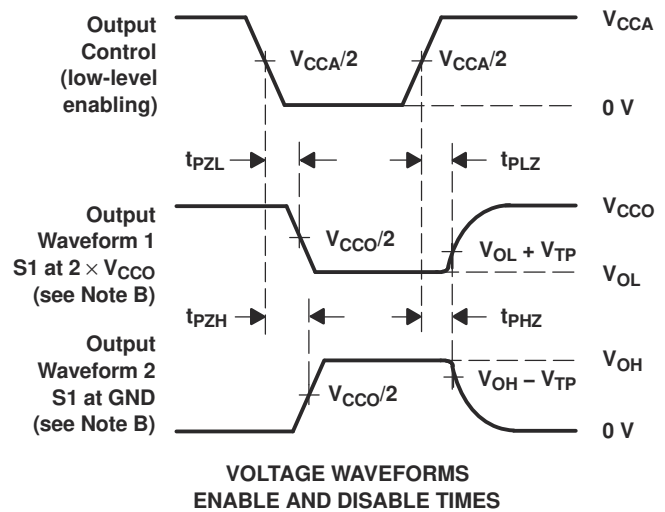
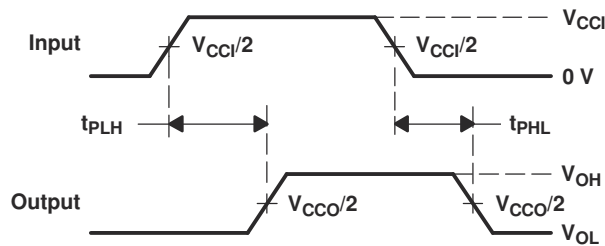
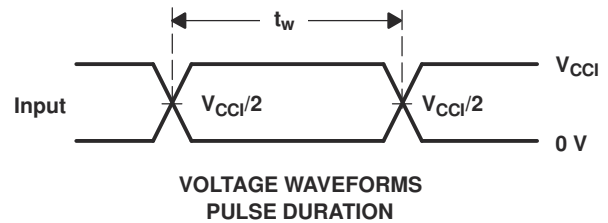
7 Parameter Measurement Information



LOAD CIRCUIT

V_{CCO}	C_L	R_L	V_{TP}
$1.8\text{ V} \pm 0.15\text{ V}$	15 pF	2 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	15 pF	2 k Ω	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	15 pF	2 k Ω	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	15 pF	2 k Ω	0.3 V

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CCO}$
t_{PHZ}/t_{PZH}	GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $dv/dt \geq 1\text{ V/ns}$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. V_{CCI} is the V_{CC} associated with the input port.
 - I. V_{CCO} is the V_{CC} associated with the output port.
 - J. All parameters and waveforms are not applicable to all devices.

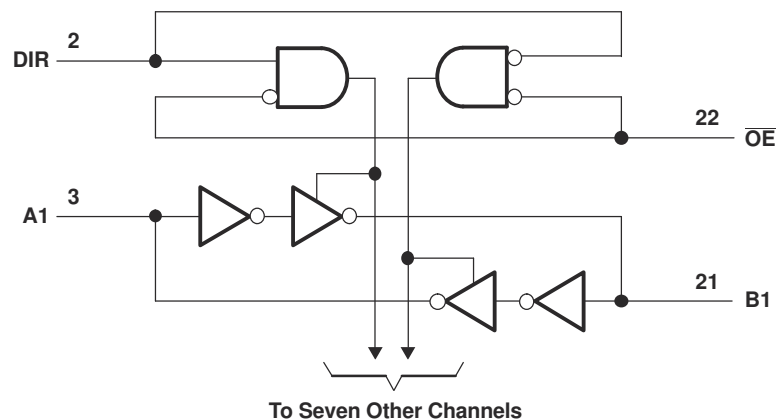
图 7-1. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The SN74LVC8T245-Q1 is an eight bit non-inverting bus transceiver with configurable dual power supply rails that enables bidirectional voltage level translation. Pin Ax and direction control pin are support by V_{CCA} and pin Bx is support by V_{CCB} . The A port is able to accept I/O voltages ranging from 1.65 V to 5.5 V, while the B port can accept I/O voltages from 1.65 V to 5.5 V. The high on DIR allows data transmission from A to B and a low on DIR allows data transmission from B to A. For voltage level translation below 1.65 V, see TI [AXC](#) products.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.65-V to 5.5-V Power-Supply Range

Both V_{CCA} and V_{CCB} can be supplied at any voltage between 1.65 V and 5.5 V making the device suitable for translating between any of the voltage nodes (1.8 V, 2.5 V, 3.3 V, and 5 V).

8.3.2 I_{off} Supports Partial-Power-Down Mode Operation

I_{off} prevents backflow current by disabling I/O output circuits when device is in partial-power-down mode. The inputs and outputs for this device enter a high-impedance state when the device is powered down, inhibiting current backflow into the device. The maximum leakage into or out of any input or output pin on the device is specified by I_{off} in the Electrical Characteristics.

8.3.3 Balanced High-Drive CMOS Push-Pull Outputs

A balanced output allows the device to sink and source similar currents. The high drive capability of this device creates fast edges into light loads so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. Two outputs can be connected together for 2X stronger output drive strength. The electrical and thermal limits defined in the Absolute Maximum Ratings must be followed at all times.

8.3.4 V_{CC} Isolation

The I/O's of both ports will enter a high-impedance state when either of the supplies are at GND, while the other supply is still connected to the device. The maximum leakage into or out of any input or output pin on the device is specified by I_{off} in the *Electrical Characteristics*.

8.4 Device Functional Modes

The SN74LVC8T245-Q1 is voltage level translator that can operate from 1.65 V to 5.5 V (V_{CCA} and V_{CCB}). The signal translation between 1.65 V and 5.5 V requires direction control and output enable control. When \overline{OE} is low and DIR is high, data transmission is from A to B. When \overline{OE} is low and DIR is low, data transmission is from B to A. When \overline{OE} is high, both output ports will be high-impedance. For voltage level translation below 1.65V, see TI [AXC](#) products.

**表 8-1. Function Table
(Each 8-Bit Section)**

CONTROL INPUTS ⁽¹⁾		OUTPUT CIRCUITS		OPERATION
\overline{OE}	DIR	A PORT	B PORT	
L	L	Enabled	Hi-Z	B data to A bus
L	H	Hi-Z	Enabled	A data to B bus
H	X	Hi-Z	Hi-Z	Isolation

(1) Input circuits of the data I/Os are always active.

9 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

9.1 Application Information

The SN74LVC8T245-Q1 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The maximum output current can be up to 32 mA when device is powered by 5 V. It is recommended to tie all unused I/Os to GND. The device should not have any floating I/Os when changing translation direction.

9.2 Typical Application

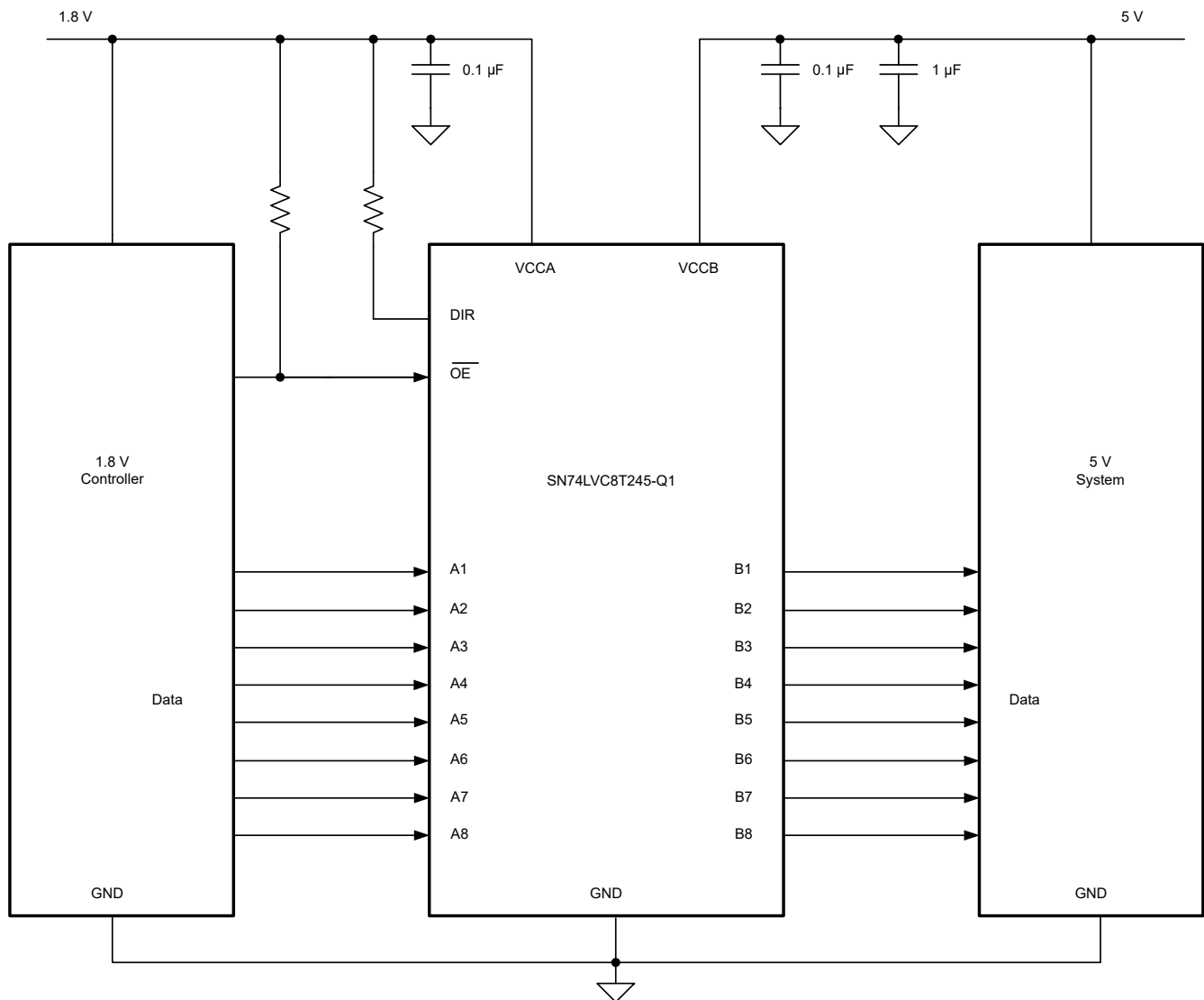


图 9-1. Typical Application Circuit

9.2.1 Design Requirements

For this design example, use the parameters listed in [表 9-1](#).

表 9-1. Design Parameters

PARAMETERS	VALUES
Input voltage range	1.65 V to 5.5 V
Output voltage	1.65 V to 5.5 V

9.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
 - Use the supply voltage of the device that is driving the SN74LVC8T245-Q1 device to determine the input voltage range. For a valid logic high, the value must exceed the V_{IH} of the input port. For a valid logic low, the value must be less than the V_{IL} of the input port.
- Output voltage range
 - Use the supply voltage of the device that the SN74LVC8T245-Q1 device is driving to determine the output voltage range.

9.2.3 Application Curve

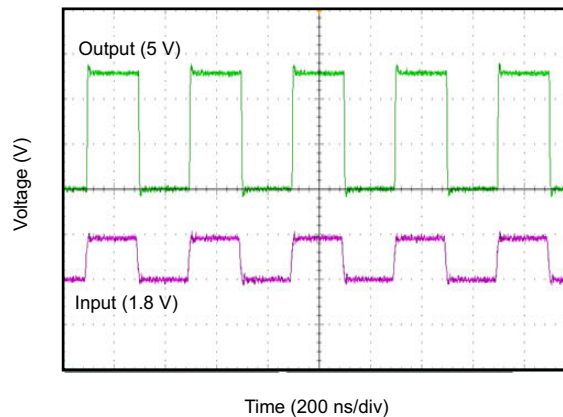


图 9-2. Translation Up (1.8 V to 5 V) at 2.5 MHz

10 Power Supply Recommendations

The SN74LVC8T245-Q1 device uses two separate configurable power-supply rails, V_{CCA} and V_{CCB} . V_{CCA} accepts any supply voltage from 1.65 V to 5.5 V and V_{CCB} accepts any supply voltage from 1.65 V to 5.5 V. The A port and B port are designed to track V_{CCA} and V_{CCB} respectively allowing for low-voltage bidirectional translation between any of the 1.8-V, 2.5 -V, 3.3-V and 5-V voltage nodes. The recommendation is to first power-up the input supply rail to help avoid internal floating while the output supply rail ramps up. However, both power-supply rails can be ramped up simultaneously.

11 Layout

11.1 Layout Guidelines

To ensure reliability of the device, following common printed-circuit board layout guidelines is recommended.

- Bypass capacitors should be used on power supplies.
- Short trace lengths should be used to avoid excessive loading.
- Placing pads on the signal paths for loading capacitors or pullup resistors helps adjust rise and fall times of signals depending on the system requirements.

11.2 Layout Example

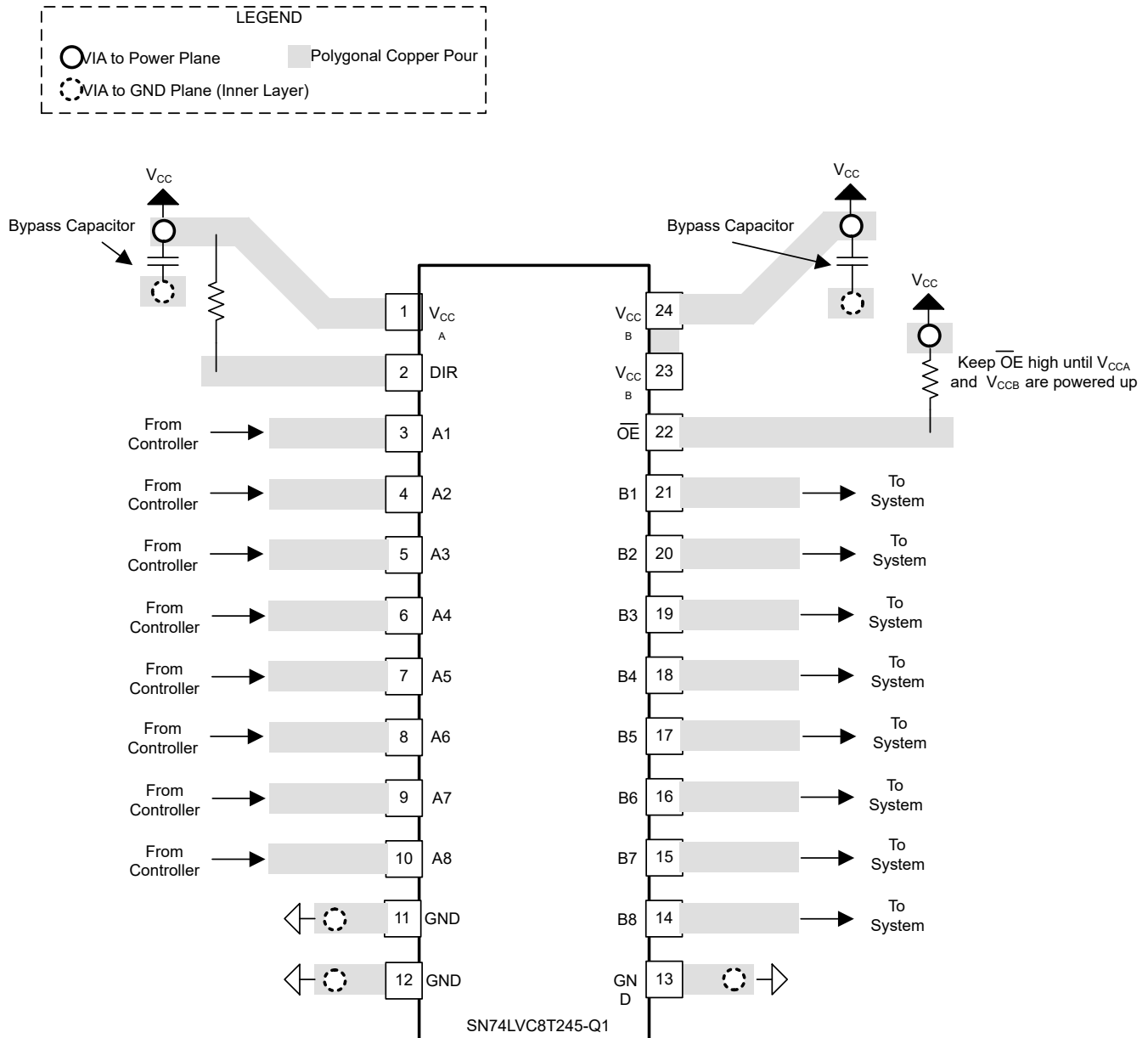


图 11-1. SN74LVC8T245-Q1 Layout

12 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

12.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

12.2 支持资源

[TI E2E™ 支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

12.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

12.5 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC8T245QPWRQ1	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	NH245Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVC8T245-Q1 :

- Catalog : [SN74LVC8T245](#)
- Enhanced Product : [SN74LVC8T245-EP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC8T245QPWRQ1	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC8T245QPWRQ1	TSSOP	PW	24	2000	356.0	356.0	35.0

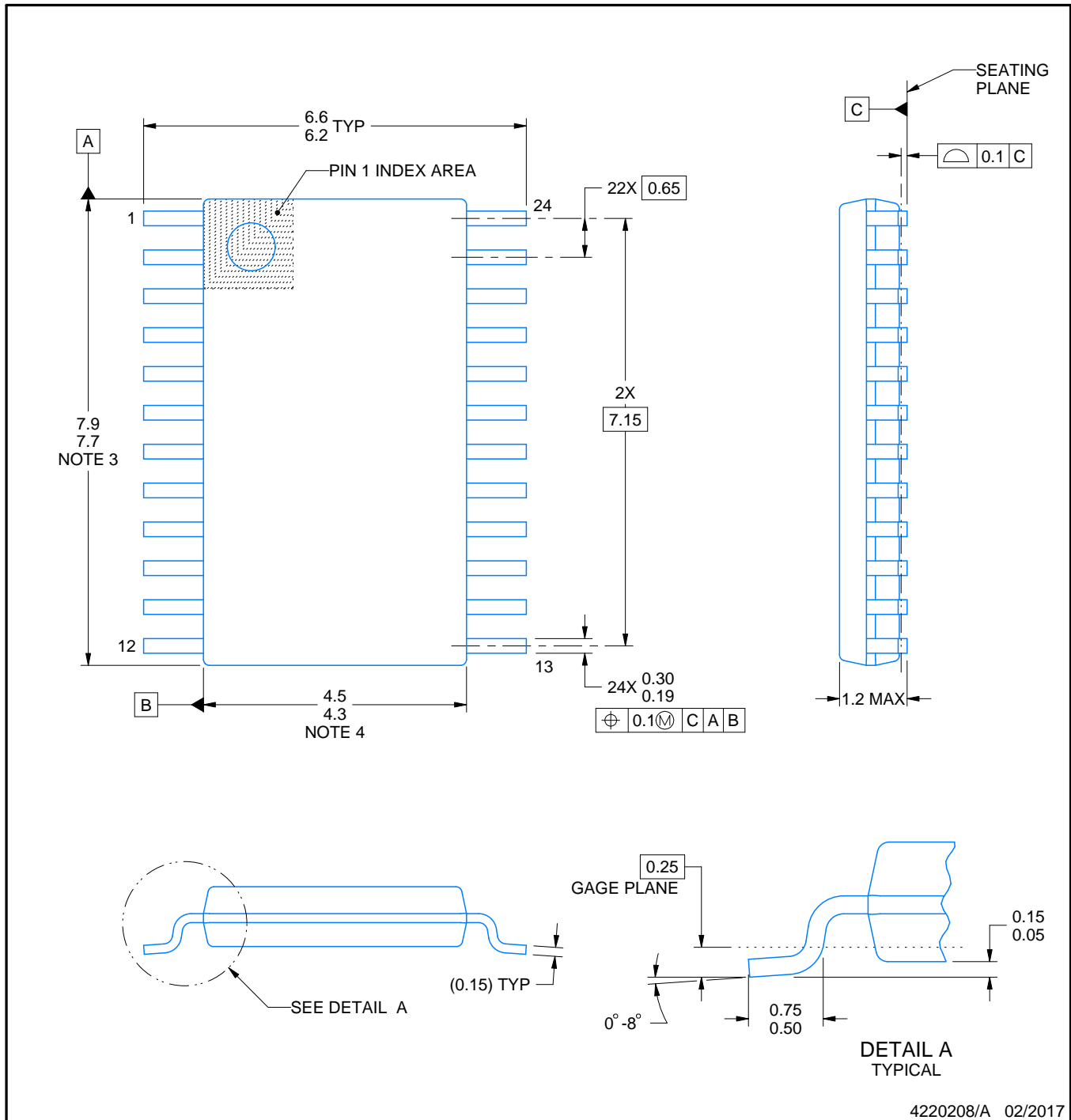
PW0024A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220208/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2023，德州仪器 (TI) 公司